

STM32WL_QFN48_LP_DirectTie_RefBoard

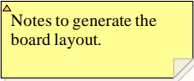
MB1789_LP

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- Sheet 1: Project overview (this page)
- Sheet 2: MB1789_LP.SchDoc

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.



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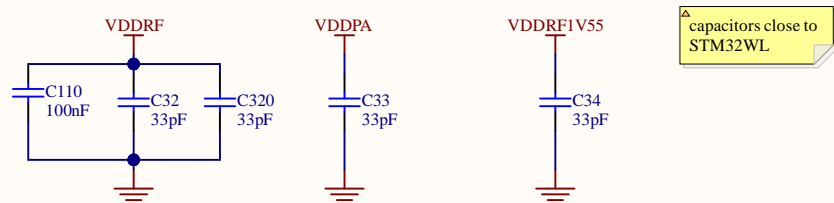
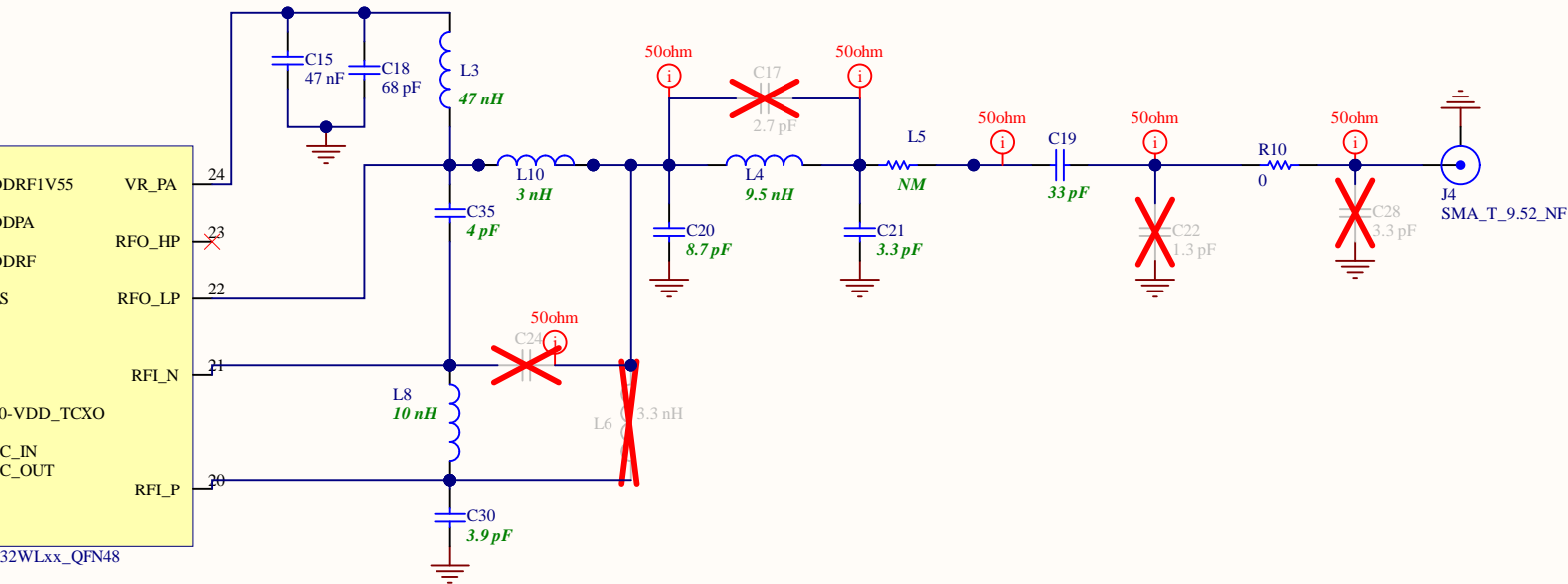
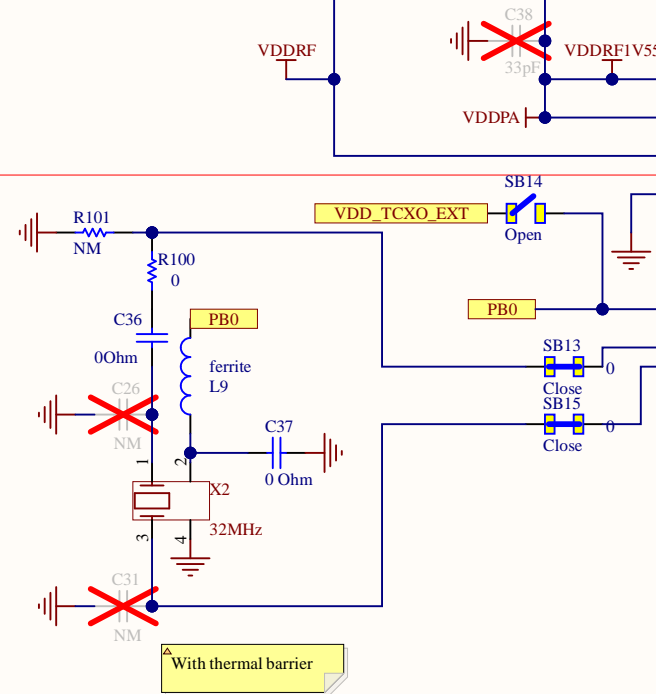
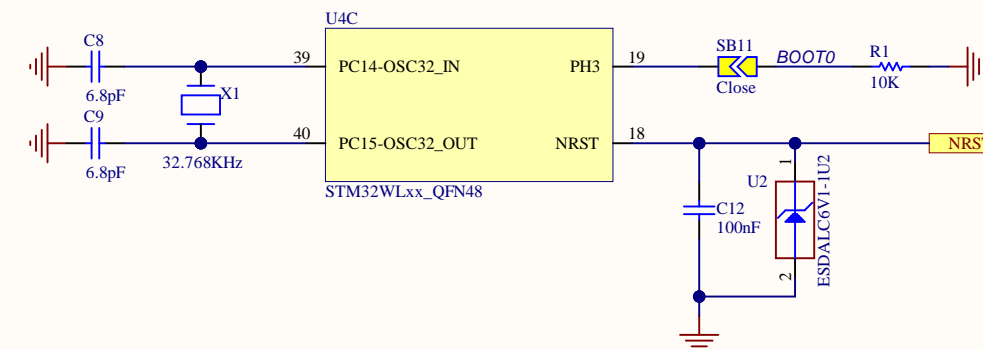
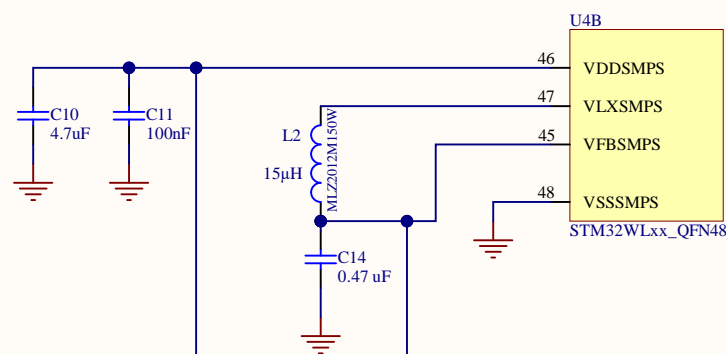
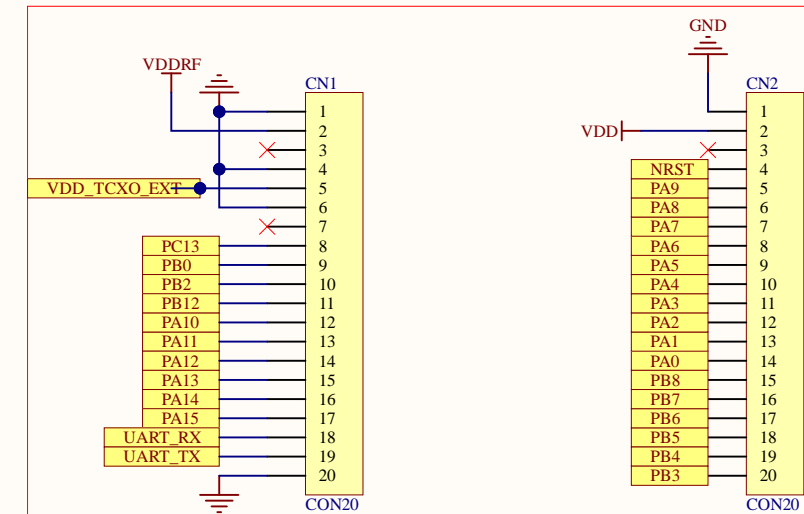
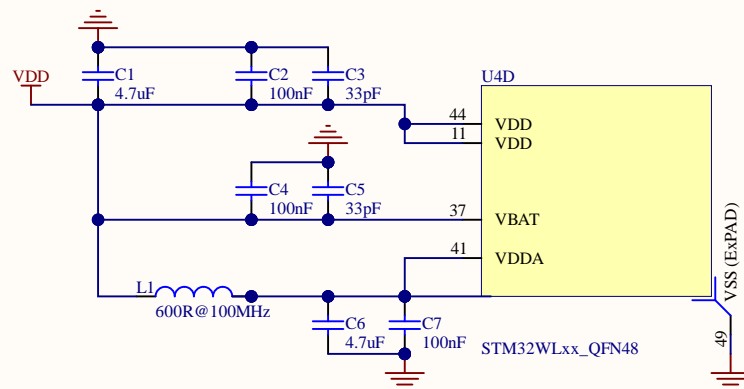
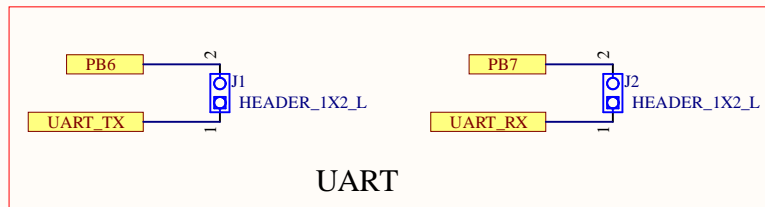
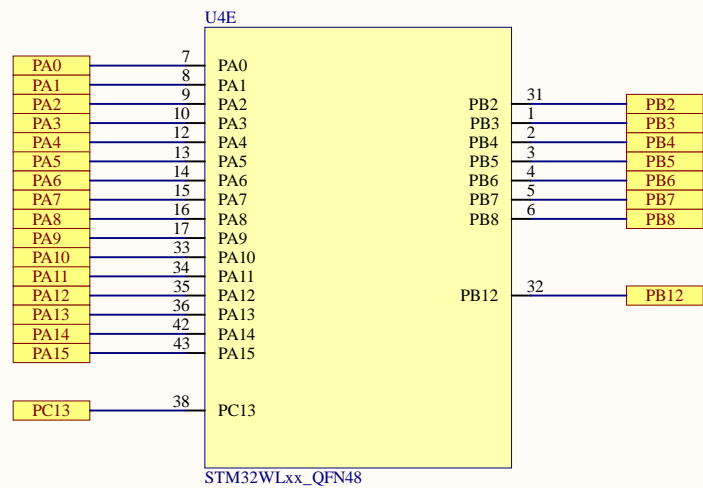
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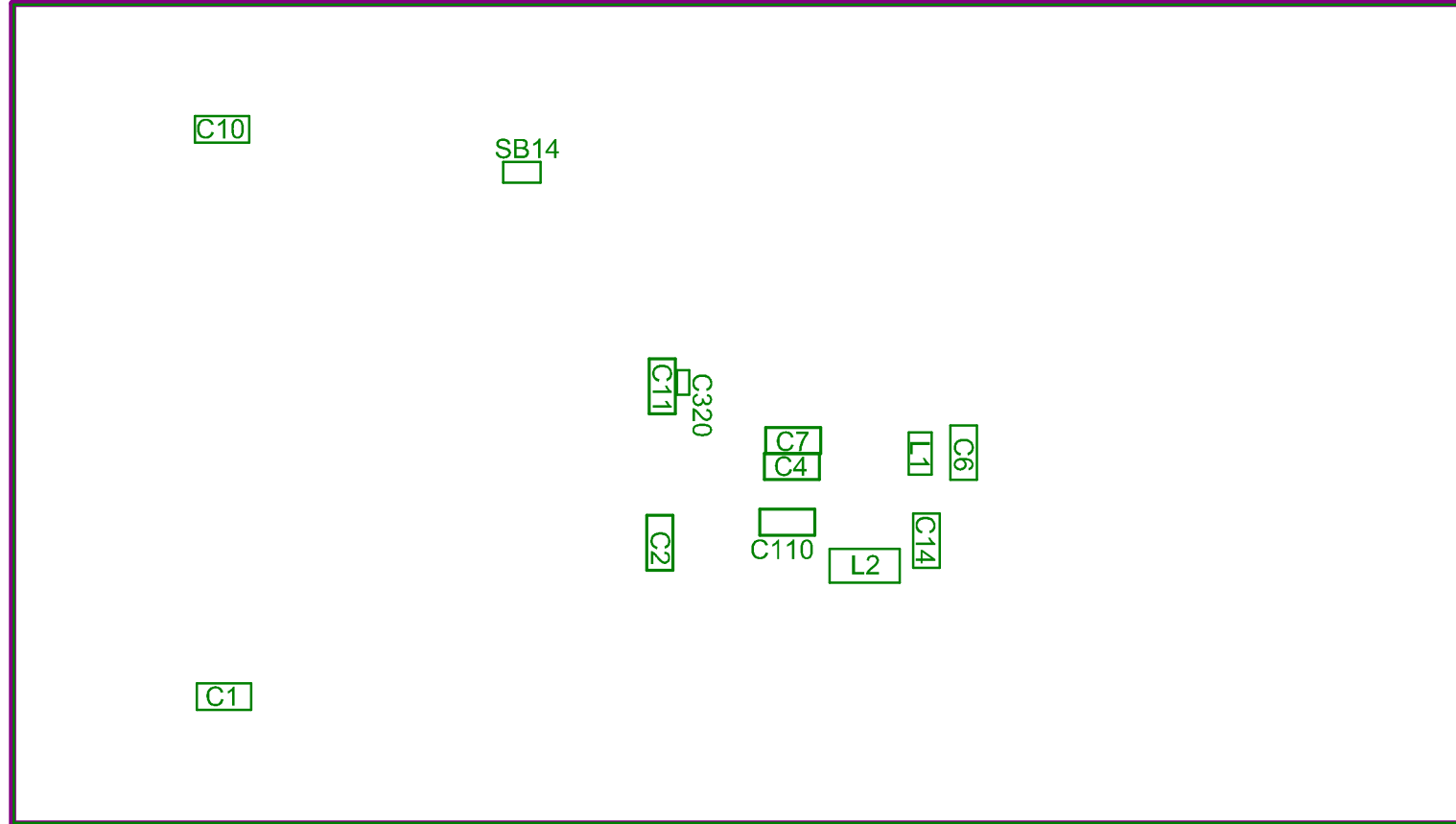
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MB1789_LP.SchDoc




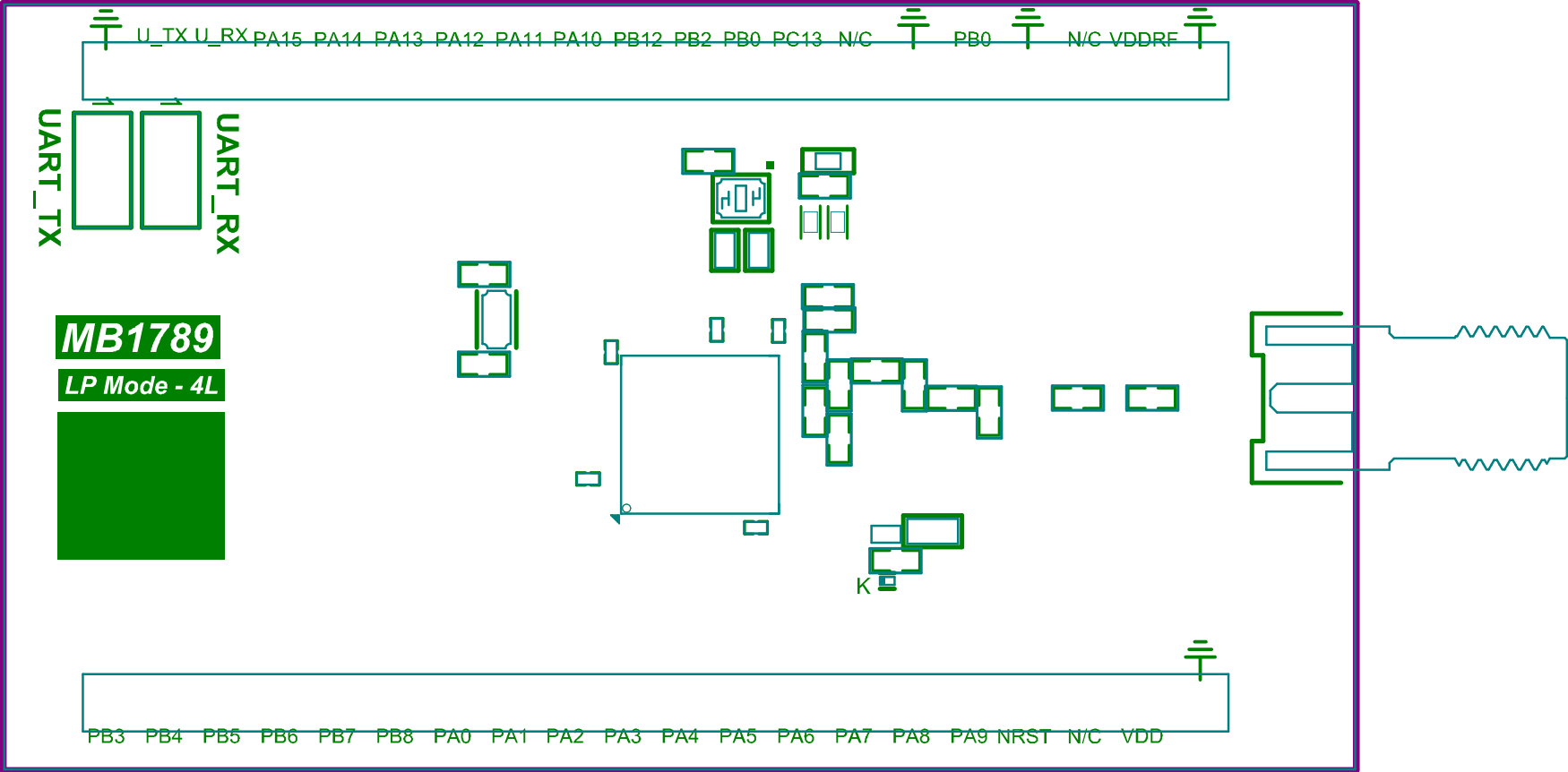
Title: Schematic sheet title to update		
Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Variant: HighBand_LowPower		
Revision: A-01		Reference: MB1789_LP
Size: A4	Date: 01-04-2022	Sheet: 1 of 1







Project: STM32WL_QFN48_LP_DirectTie_RefBoard		
Layer: Bottom Assembly	Gerber: .GM15	
Variant: HighBand_LowPower	Ref: MB1789_LP	
Date: 01-04-2022	Rev: A	



Top Overlay

.GTO

